| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 1 | 1239 | 438/690,691,692.ccls. | USPAT | 2002/06/17 12:18 |
| 2 | 971 | 438/623,624.ccls. | USPAT | 2002/06/17 12:19 |
| 3 | 295 | 438/626.ccls. | USPAT | 2002/06/17 12:19 |
| 4 | 248 | 438/715,716.ccls. | USPAT | 2002/06/17 12:19 |
| 5 | 1 | leong-lup$.in. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/06/17 12:19 |
| 6 | 23600 | planar$8 and heat$3 and pressure and mechan$4 and (layer film wafer substrate) | USPAT | 2002/06/17 12:26 |
| 7 | 5156 | (planar$8 and heat$3 and pressure and mechan$4 and (layer film wafer substrate) ) and (planar$8 same heat$3) | USPAT | 2002/06/17 12:24 |
| 8 | 3442 | ( (planar$8 and heat$3 and pressure and mechan$4 and (layer film wafer substrate) ) and (planar$8 same heat$3)) and (planar$8 same (layer film wafer substrate)) | USPAT | 2002/06/17 12:25 |
| 9 | 1288 | ((( planar$8 and heat$3 and pressure and mechan$4 and (layer film wafer substrate) ) and (planar$8 same heat$3)) and (planar$8 same (layer film wafer substrate)) ) and (planar$8 same mechan$4) | USPAT | 2002/06/17 12:28 |
| 10 | 58 | planar$8 and heat$3 and pressure and mechan$4 and (layer film wafer substrate) | EPO; JPO; DERWENT; IBM_TDB | 2002/06/17 12:27 |
| 11 | 2248 | planar$8 and heat$3 and pressure and mechan$4 and (layer film wafer substrate) | US-PGPUB | 2002/06/17 12:27 |
| 12 | 467 | (planar$8 and heat$3 and pressure and mechan$4 and (layer film wafer substrate) ) and (planar$8 same heat$3) | US-PGPUB | 2002/06/17 12:27 |
| 13 | 727 | ((( (planar$8 and heat$3 and pressure and mechan$4 and (layer film wafer substrate) ) and (planar$8 same heat$3)) and (planar$8 same (layer film wafer substrate)) ) and (planar$8 same mechan$4) ) and (planar$8 same pressure) | USPAT | 2002/06/17 12:29 |